



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

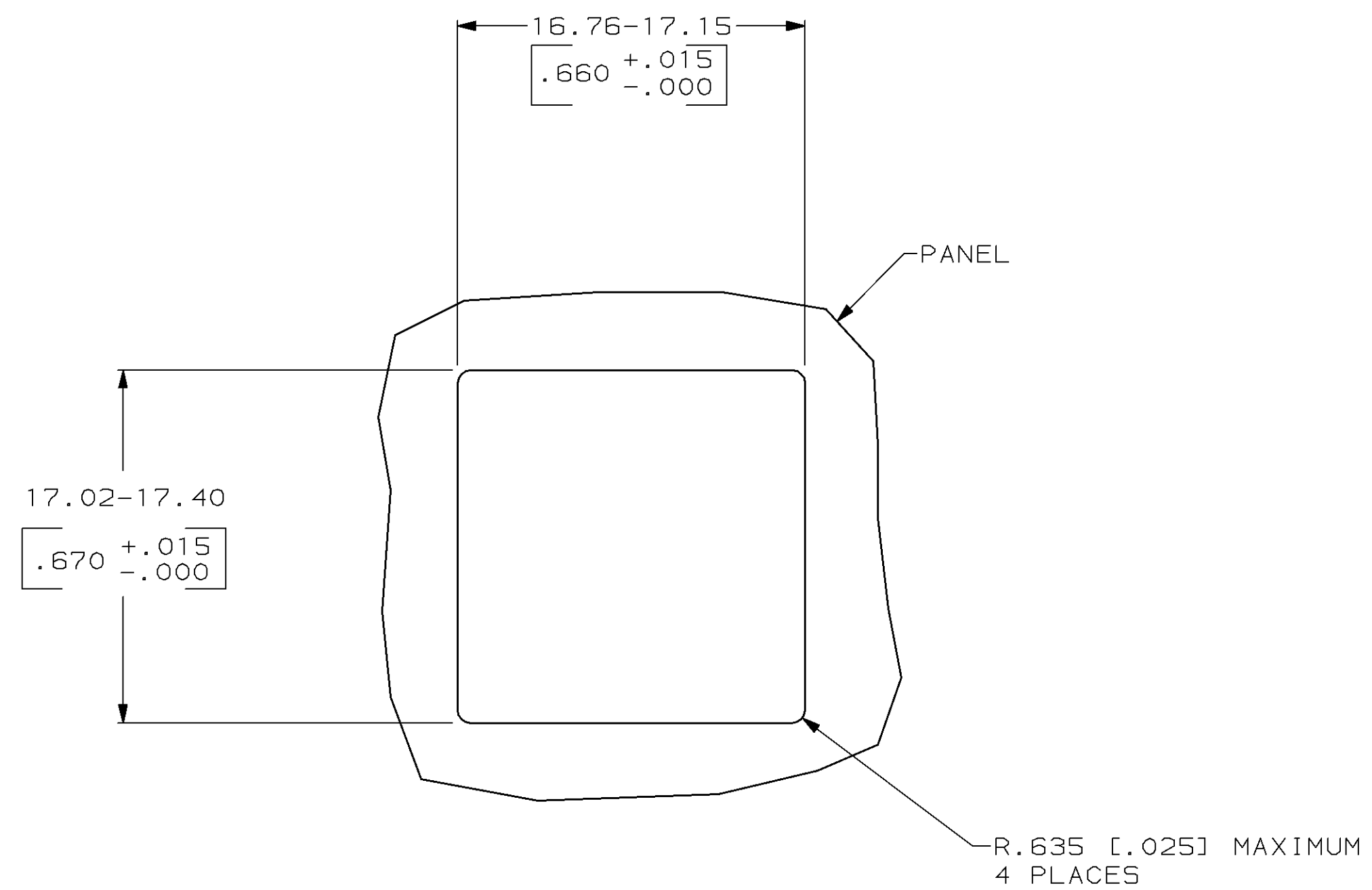
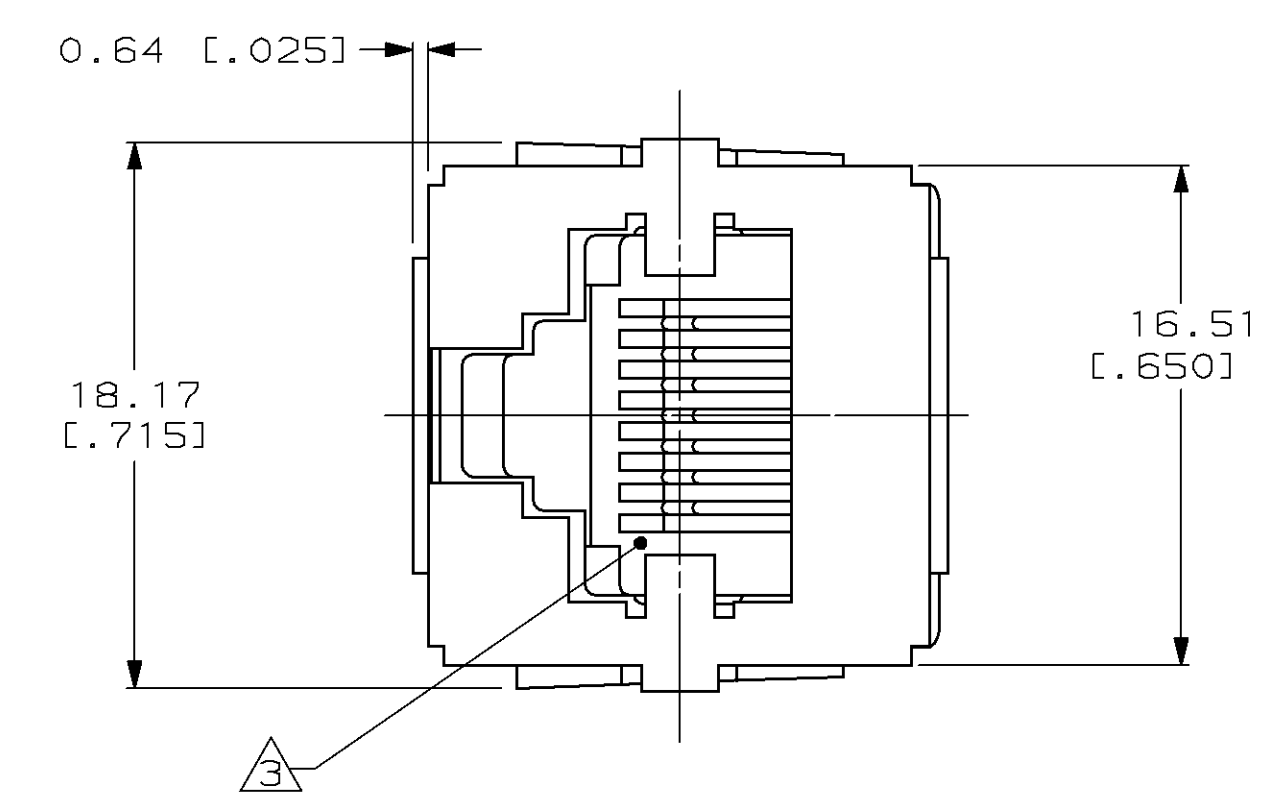
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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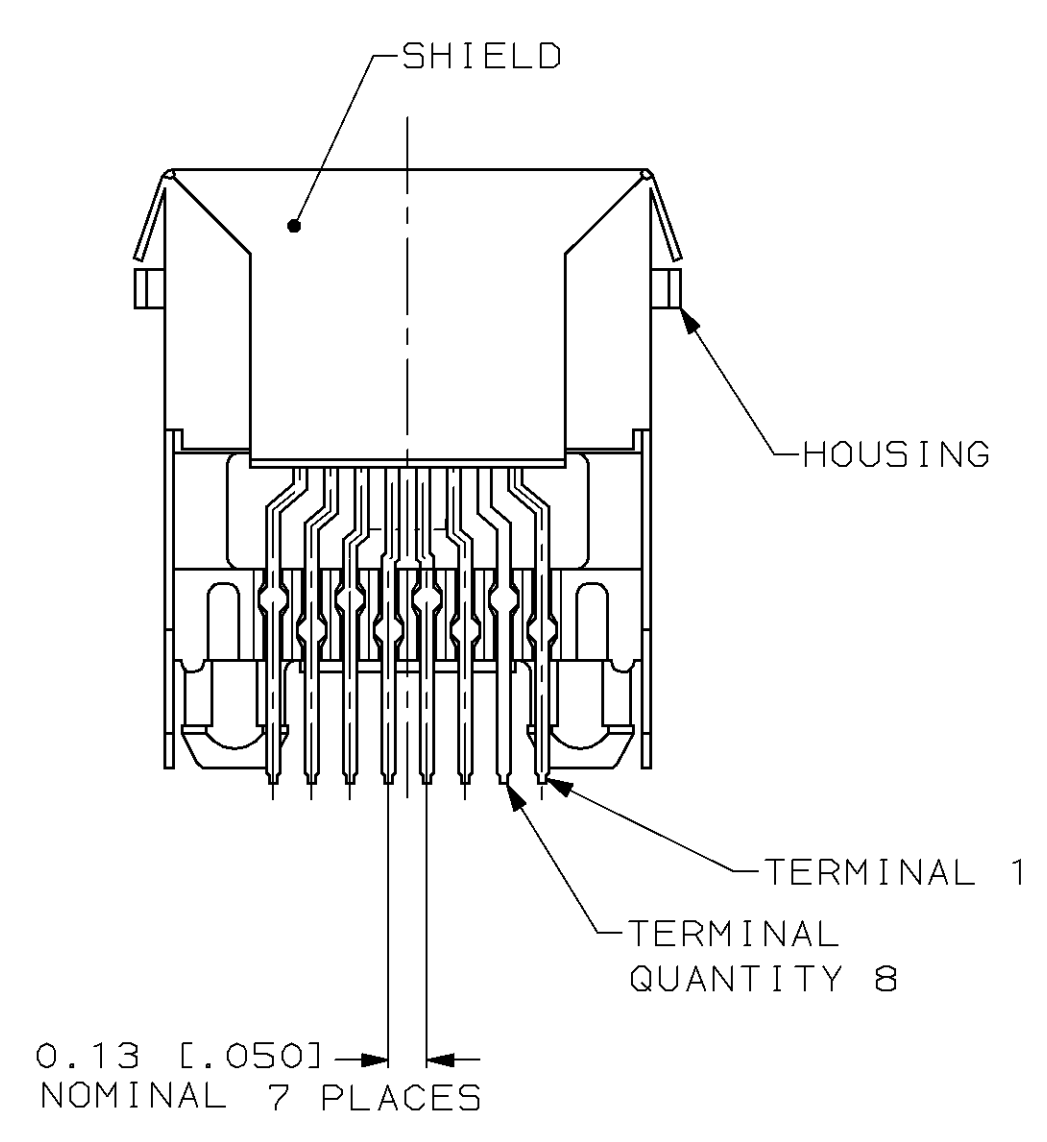
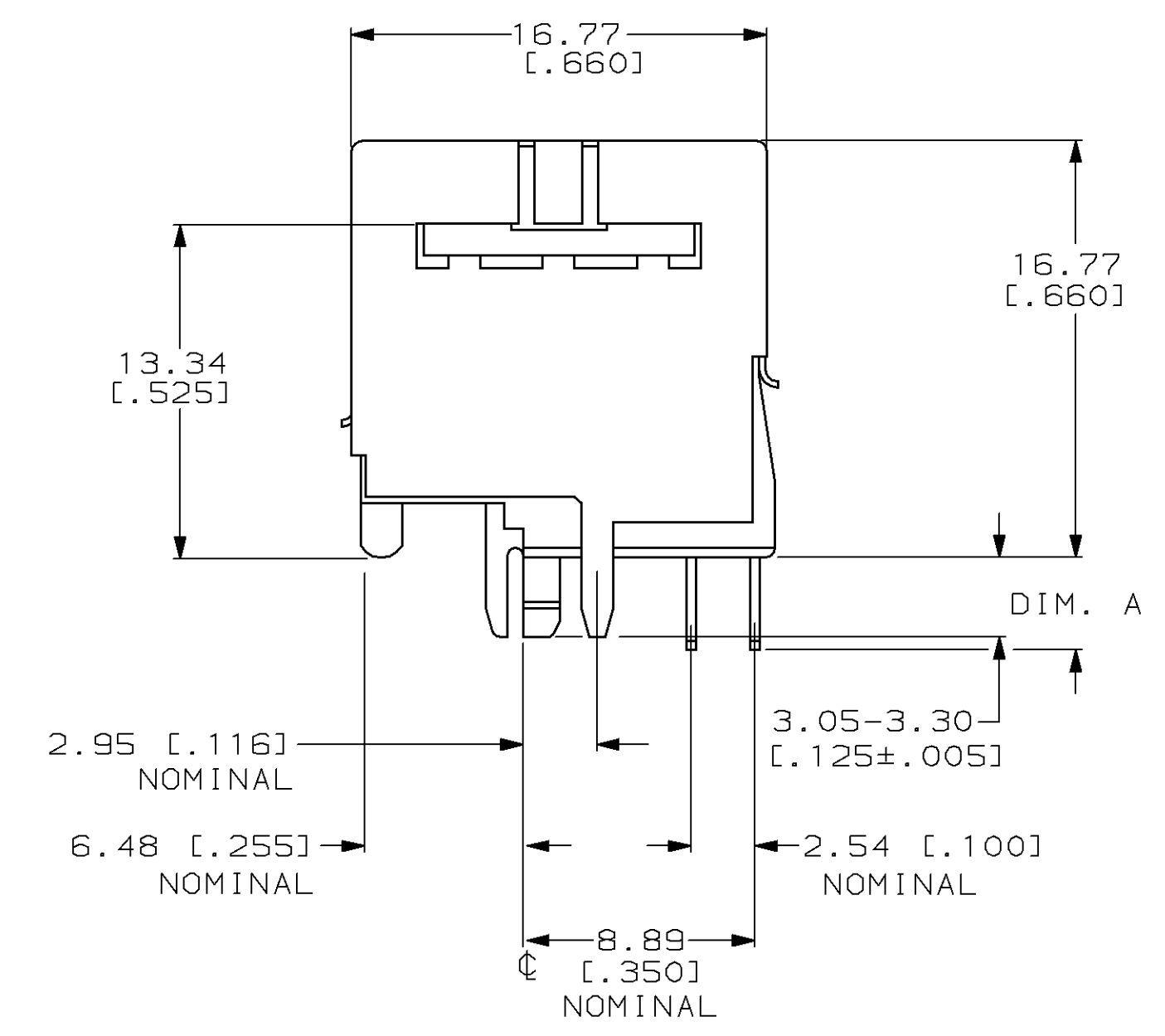
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



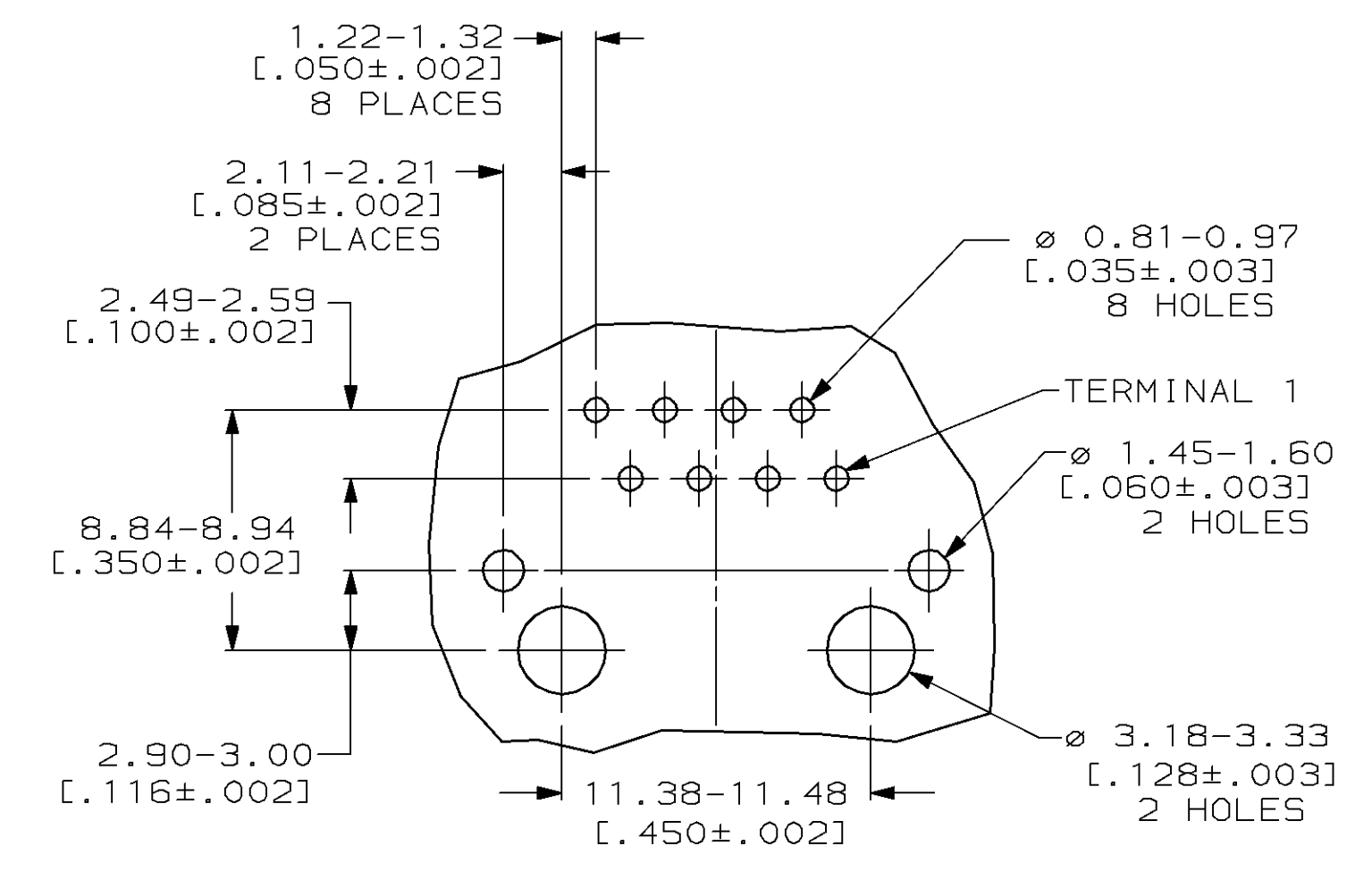
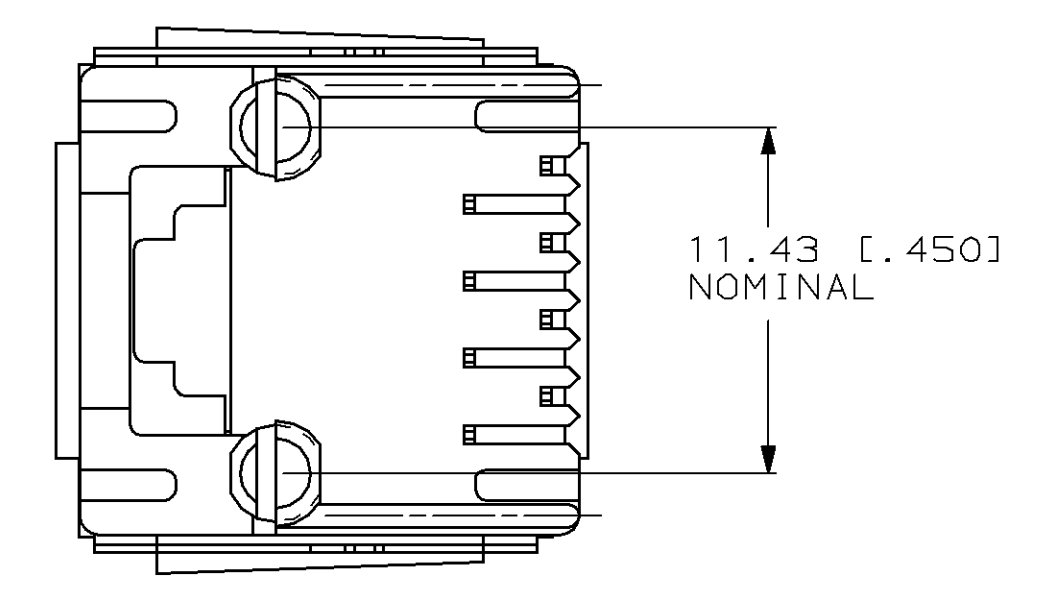
LOC		DIST		P		F		ZONE		LTR		REVISIONS		
AA	22											DESCRIPTION	DATE	APPD
												REV; EC 0210-0231-96	6-5-96	LM/UTA



- 1 DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 2 MATERIAL: HOUSING- POLYESTER MOLDING COMPOUND, BLACK.  
 TERMINALS- 0.350 [0.0138] THICK PHOS BRONZE PLATED WITH 1.27µm [0.00050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm [0.000150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.  
 SHIELD- COPPER ZINC ALLOY PLATED WITH 2.03µm [0.00080] MINIMUM THICK TIN-LEAD OVER 2.54µm [0.00100] MINIMUM THICK COPPER UNDERPLATE.
- 3 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLITIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.



SUGGESTED PANEL CUTOUT



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 NONCOMPONENT SIDE SHOWN

2.79-3.30 [0.120±0.010]	557969-2
2.92-3.94 [0.135±0.020]	557969-1
DIM. A	PART NO

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON:	DR 6-16-93 B. SIMPSON	<b>AMP</b> AMP Incorporated Harrisburg, PA 17105-3608
2 PLC DEC ± -	CHK 6-24-93 B. FOX	
3 PLC DEC ± -	APPD 6-24-93 J. TONEY	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS
ANGLES ± -	APPD 6-24-93 H. MCGRATH	PRODUCT SPEC 108-1163
MATERIAL	APPLICATION SPEC 114-2048	SIZE D 00779
FINISH	WEIGHT -	CAGE CODE 00779
		DRAWING NO C-557969
		SCALE 4:1
		SHEET 1 OF 1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.